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CONFIRMATION NO. 2570

SERIAL NUMBI 10/632,550	ER	}		LASS 257	GROUP ART U 2818		JNIT	D	TTORNEY OCKET NO. PAC 1017-7
APPLICANTS									
Marcos Karnezos, Palo Alto, CA;									
** CONTINUING DATA **********************************									
** FOREIGN APPLICATIONS ************************************									
IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** 10/31/2003									
00 000 He (a-d) conditions : vec I no Met after Allewance						SHEETS T		OTAL INDEPENDENT	
met Verified and Acknowledged	Exa	Malluon	nitials	COUNTRY CA	DR	DRAWING 8		IMS 7	CLAIMS 2
ADDRESS 22470 HAYNES BEFFEL & WOLFELD LLP P O BOX 366 HALF MOON BAY , CA 94019									
TITLE Semiconductor multi-package module including stacked-die package and having wire bond interconnect between stacked packages									
	FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following:					☐ All Fees			
FILING FEE						☐ 1.16 Fees (Filing) ☐ 1.17 Fees (Processing Ext. of time)			
RECEIVED						1.18 Fees (Issue)			
900					Other				
					☐ Credit				